

PATENTS
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IN THE CLAIMS:

Claims 1-17 (canceled)

1 Claim 18 (currently amended). A substrate for receiving a die-down die and pro-
2 viding electrical contacts re-orientated into a die-up orientation, the die-down die defin-
3 ing electrical contacts, the substrate comprising:
4 a plurality of electrically conductive traces defining first contacts, the first
5 contacts arranged to accept connector wires making electrical connections from the elec-
6 trical contacts of a single die-down die, and
7 wherein the electrical traces define second contacts, the second contacts arranged
8 to correspond to the die-up orientation of a single die-up die,
9 wherein the substrate can be placed into a package designed to accept a single die-
10 up die, and wherein electrical connections may be made to the substrate's second contacts
11 as if it were a single die-up die.

1 Claim 19 (currently amended). The substrate of claim 18 further comprising:
2 a single die-down die mounted to the substrate,
3 connector wires joining the electrical contacts of the die-down die to the
4 first contacts on the conductive traces,
5 and
6 electrically conductive wires joining the second contacts on the conductive
7 traces to contacts on a lead frame.

1 Claim 20. (canceled).

1 Claim 21. (currently amended). The substrate of claim 19 further comprising
2 non-conductive means for attaching the substrate to the single die-down die.

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1 Claim 22. (previously presented). The substrate of claim 18 wherein the substrate
2 comprises a material selected from the groups consisting of ceramic and organic.

1 Claim 23. (currently amended). The substrate of claim 19 wherein the single die-
2 down die is an integrated circuit.

1 Claim 24. (canceled).

1 Claims 25-31 (withdrawn).

1 Claim 32 (deleted).

1 Claim 33. (deleted).

1 Claim 34. (currently amended). The die attach package of claim 45 further com-
2 prising non-conductive means for attaching the substrate to a the single die-down die.

1 Claim 35. (previously presented). The die attach package of claim 45 wherein the
2 substrate comprises a material selected from the groups consisting of ceramic and or-
3 ganic.

1 Claim 36. (currently amended). The die attach package of claim 45 wherein the
2 single die-down die is an integrated circuit.

1 Claim 37. (currently amended). The die attach package of claim 45 wherein the
2 single die-down die includes components attached to the die-down die.

Claim 38-44. (Withdrawn).

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1 Claim 45 (currently amended). A die attach package for receiving a single die
2 with contacts arranged in a die-up orientation, the die attach package comprising:
3 a substrate as defined in claim 18,
4 a lead frame with contacts,
5 connector wires joining the second contacts on the traces to the lead frame
6 contacts, ~~wherein the lead frame also provides means to make electrical connection to a~~
7 ~~printed circuit board.~~